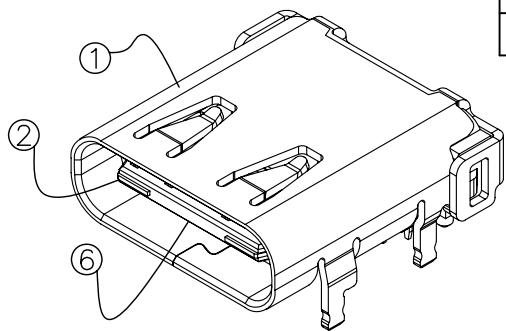
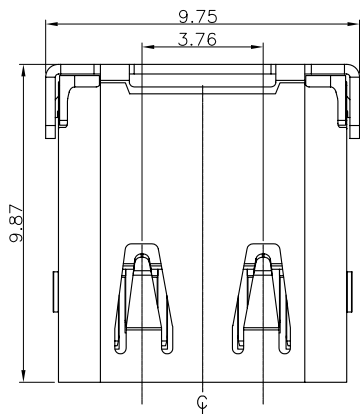


| REV | ECN NO. | DISCRIPTION | CHEKED/DATE | APPD/DATE |
|-----|---------|-------------|-------------|-----------|
| | | | | |
| | | | | |

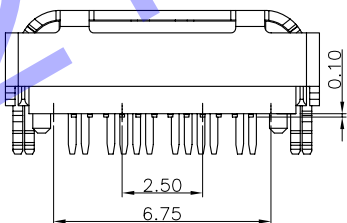
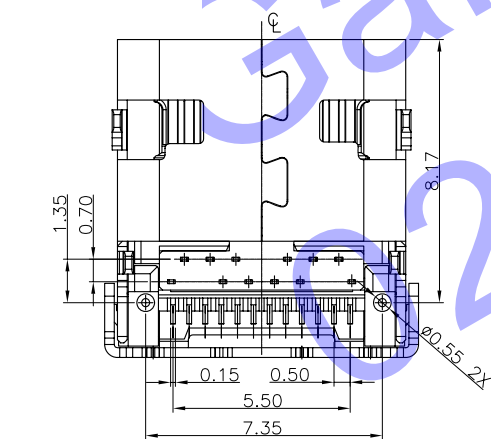
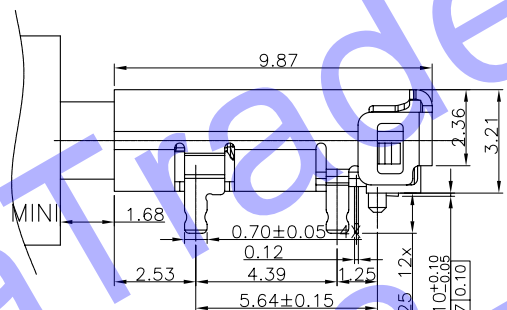
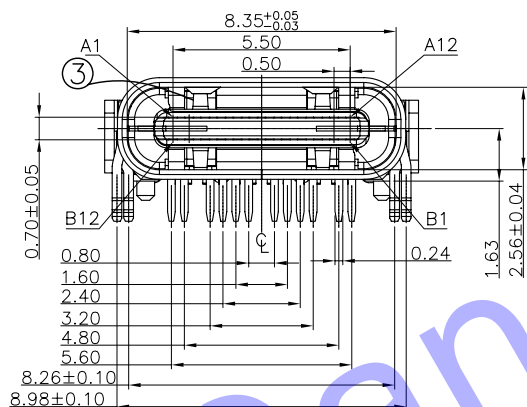


NOTES: 1.MATERIAL:
MOLDING: LCP UL94 V-0
CONTACT: COPPER ALLOY.
GOLD PLATED Min ON CONTACT AREA, 100u"
Min TIN (LEAD FREE) ON SOLDER AREA,
SHELL: SUS304-H,T=0.30±0.03mm
50u" NICKEL PLATING OVER ALL.
SHILD: SUS304-H,T=0.12±0.03mm

2.MECHANICAL:
INSERTION: 5~20N.
EXTRACTION: 8~20N AFTER TEST.
DURABILITY: 10000 CYCLES

3.ELECTRICAL:
CURRENT: 5A FOR VBUS;
1.25A FOR GND PIN.
0.25A FOR OTHER.
VOLTAGE: 20 V MAX
WITHSTANDING VOLTAGE: 100V AC R.M.S.
CONTACT RESISTANCE: 40mΩ MAX.
INSULATION RESISTANCE: 100MΩ MIN.

4.ENVIRONMENTAL
TEMPERATURE RANGE -25°C ~ +85°C



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| | | | | |
|------------|------------|------|-------------|-------------------------------------|
| .X:±0.25 | X.:±1' | APP. | DWG NO. | Z3.1-02-1 |
| .XX:±0.15 | .X:±0.5' | CHK. | TITLE | USB 3.1 C TYPE DIP+SMT母座 四脚插板大窗口 |
| .XXX:±0.05 | .XX:±0.02' | DGN. | 朱远明15.11.28 | SERIES |
| UNIT mm | SCALE 1:1 | DRW. | 朱远明15.11.28 | |
| REV. A0 | SHEET: 1/1 | | | |

A

B

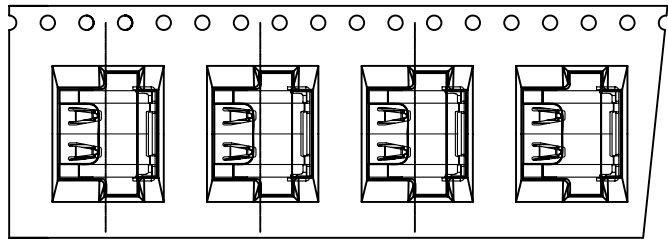
C

D

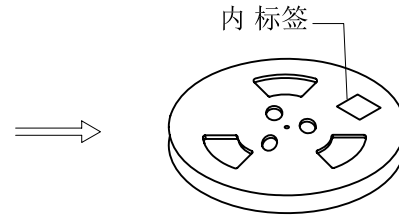
E

F

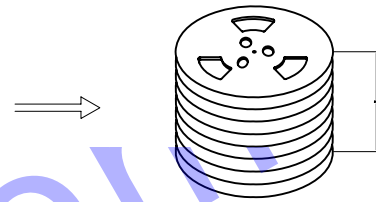
| REV | ECN NO. | DISCRIPTION | DRAWN/DATE | CHEKED/DATE | APPROVED/DATE |
|-----|---------|-------------|------------|-------------|---------------|
| | | | | | |
| | | | | | |



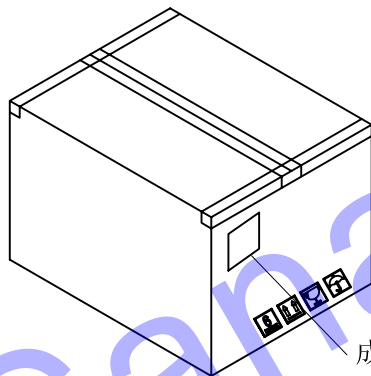
① 产品入载带示意图



② 卷盘贴标签示意图

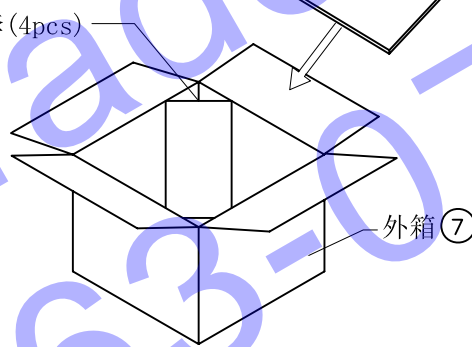


③ 7盘产品叠层示意图



⑥ 外箱封箱示意图

成品标签



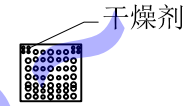
⑤ 产品入外箱示意图

图四

纸板(2pcs) ⑤
分别放在外箱底面
和最上面

封口面
防水袋封口面朝上

⑧ 防水袋



干燥剂

④ 7盘产品入防水袋示意图

图三

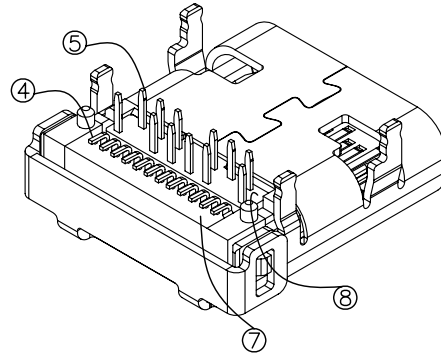
包装说明:

1. 将检验好的成品;SMT朝下放入载带底部;每卷装1000PCS产品;具体如图一所示
2. 将包装好的产品;每盘必需贴上内标签;具体如图二所示
3. 将贴好内标签的产品每8盘叠一层装入防水袋中并加一包干燥剂;装好后将防水袋封好;具体如图三图四所示
4. 先将1pcs平卡放入纸箱底部;然后将装好产品的防水袋装入纸箱中;防水袋热熔封口,封口面需朝上;并将4PCS三角套分别装入4个角;如图五所示
5. 装好后将1pcs平卡放入纸箱最上面并封好纸箱及贴好相关标签;具体如图六所示;(产品包装的标签,如客户有要求,请按客户要求包装出货)
6. 载带前面留30PCS空格,后面留20PCS空格
7. COVER与CARRY剥离力:50-125g,速度:300mm/分钟左右,剥离角度:165°-180°

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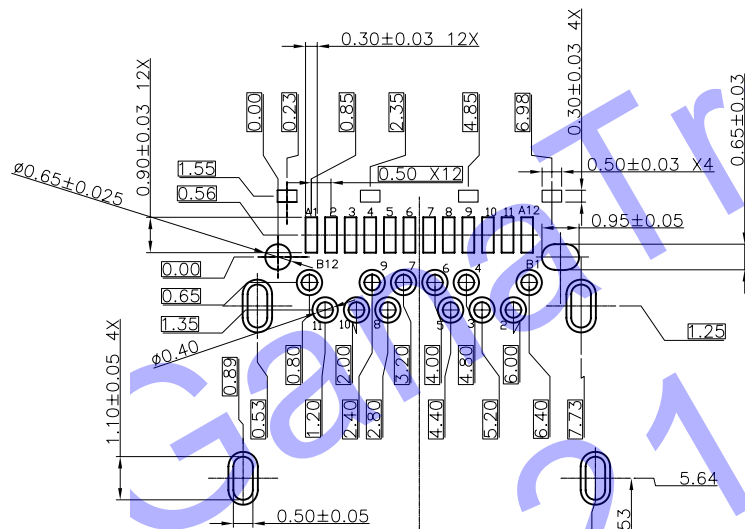
| | | | | | |
|------------|------------|--------|----------------|---------|---------------------|
| .X :±0.50 | X. :±1' | APP. | | PART NO | UC2001(CU) |
| .XX :±0.30 | .X :±0.5' | CHK. | | TITLE | USB 3.1 C TYPE母座卷装图 |
| .XXX:±0.25 | .XX:±0.02' | DGN. | 朱远明 2015.04.20 | SERIES | |
| UNIT | mm | DRW. | 朱远明 2015.04.20 | | |
| SCALE | 1:1 | | | | |
| REV. | A0 | SHEET: | 1/1 | | |

| REV | ECN NO. | DISCRIPTION | CHEKED/DATE | APPD/DATE |
|-----|---------|-------------|-------------|-----------|
| | | | | |
| | | | | |



USB TYPE-C FULL-FEATURED RECEPTACLE INTERFACE PIN ASSIGNMENTS

| PIN | Signal Name | Description | PIN | Signal Name | Description |
|-----|-------------|---|-----|-------------|---|
| A1 | GND | Ground return | B12 | GND | Ground return |
| A2 | SSTXp1 | Positive half of first SuperSpeed TX differential pair | B11 | SSRXp1 | Positive half of first SuperSpeed RX differential pair |
| A3 | SSTXn1 | Negative half of first SuperSpeed TX differential pair | B10 | SSRXn1 | Negative half of first SuperSpeed RX differential pair |
| A4 | VBUS | Bus Power | B9 | VBUS | Bus Power |
| A5 | CC1 | Configuration Channel | B8 | SBU2 | Sideband Use (SBU) |
| A6 | Dp1 | Positive half of the USB 2.0 differential pair-Position 1 | B7 | Dn2 | Negative half of the USB 2.0 differential pair-Position 2 |
| A7 | Dn1 | Negative half of the USB 2.0 differential pair-Position 1 | B6 | Dp2 | Positive half of the USB 2.0 differential pair-Position 2 |
| A8 | SBU1 | Sideband Use (SBU) | B5 | CC2 | Configuraation Channel |
| A9 | VBUS | Bus Power | B4 | VBUS | Bus Power |
| A10 | SSRXn2 | Negative half of second SuperSpeed RX differential pair | B3 | SSTXn2 | Negative half of second SuperSpeed TX differential pair |
| A11 | SSRXp2 | Positive half of second SuperSpeed RX differential pair | B2 | SSTXp2 | Positive half of second SuperSpeed TX differential pair |
| A12 | GND | Ground return | B1 | GND | Ground return |



CONNECTOR FRONT EDGE
 RECOMMENDED P.C.B. LAYOUT (T:1.00mm)
 TOLERANCE UNSPECIFIED ±0.05mm

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| | | | | |
|------------|------------|------|-------------|-----------------------------------|
| .X:±0.25 | X.:±1° | APP. | DWG NO. | Z3.1-02-1 |
| .XX:±0.15 | .X:±0.5° | | | |
| .XXX:±0.05 | .XX:±0.02° | CHK. | TITLE | USB 3.1 C TYPE R/A SMT PCB LAYOUT |
| UNIT mm | | DGN. | 朱远明14.11.28 | SERIES |
| SCALE 1:1 | | DRW. | 朱远明14.11.28 | |
| REV. A0 | SHEET: 2/2 | | | |